

3M to Present Paper on New Organic Composite Dielectric Material in High-Performance IC Packages at 55th Annual ECTC

Electronic Components and Technology Conference

A new resin-coated copper (RCC) composite dielectric material for cost effective, high-performance organic chip package substrates will be the topic of a paper presented by 3M Electronics at the 55th annual Electronic Components and Technology Conference in Lake Buena Vista, Fla. The technical conference and exhibit will be held May 31-June 3 at the Wyndham Palace Resort and Spa. 3M Electronics is exhibiting in Booths 510 and 508.

The presentation "A New Organic Composite Dielectric Material for High Performance IC Packages" will take place June 3 at 2:20 p.m. Shichun Qu, product development specialist, 3M Electronics, Electronic Solutions Division, leads the presenting team. The new RCC material from 3M features a low dielectric constant and ultralow loss factor. Key properties of this new dielectric material are:

- Toughened, high Tg (235 degrees Celsius) thermosetting resin with low Dk (3.2) and Df (0.002)
- Ultralow moisture absorption (less than 0.14 percent)
- Low isotropic CTE (32 ppm/degrees Celsius) in a broad temperature range
- Engineered interfaces at all levels
- Excellent manufacturability, such as laser ablation characteristic and flow/fill properties

The new dielectric material is used in 3M ultrathin profile multilayer IC substrates, which are currently being evaluated at various customer sites around the world.

For additional information about this product from 3M, visit <http://www.3M.com/dielectric>.

About 3M Electronics

3M Electronics, co-located in Austin, Texas and St. Paul, Minn., has numerous technologies and provides a wide range of products for the electronics market. The business provides products and solutions to meet the electronic industry's challenges of protecting sensitive components and precisely delivering them to the assembly point, such as carrier and cover tapes and trays, as well as flexible and multilayer microinterconnect packaging solutions; embedded capacitor materials; copper and fiber interconnect systems; cables and cable assemblies; static control products, Textool test and burn-in sockets; tapes, abrasives, chemicals and materials, and ceramic textiles and composites.

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